

HAT1094C

Silicon P Channel MOS FET Power Switching

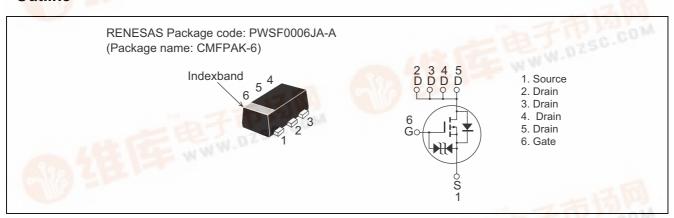
REJ03G1231-0400 Rev.4.00 Feb 28, 2006

WWW.DZSC

Features

- Low on-resistance $R_{DS(on)} = 67 \text{ m}\Omega \text{ typ. (at } V_{GS} = -4.5 \text{ V})$
- Low drive current.
- 1.8 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to Source voltage	V_{DSS}	-12	V	
Gate to Source voltage	V _{GSS}	±8	V	
Drain current	I _D	-2.5	А	
Drain peak current	I _D (pulse) ^{Note1}	-10	A	
Body - Drain diode reverse drain current	I _{DR}	-2.5	A	
Channel dissipation	Pch ^{Note 2}	850	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 $40 \times 40 \times 1.6$ mm), Ta = 25°C



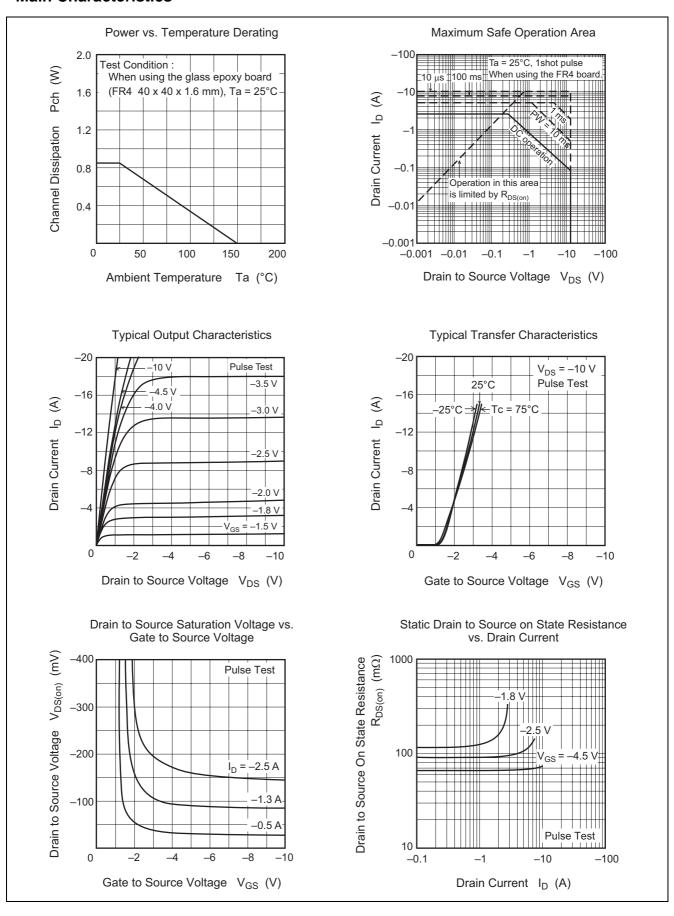
Electrical Characteristics

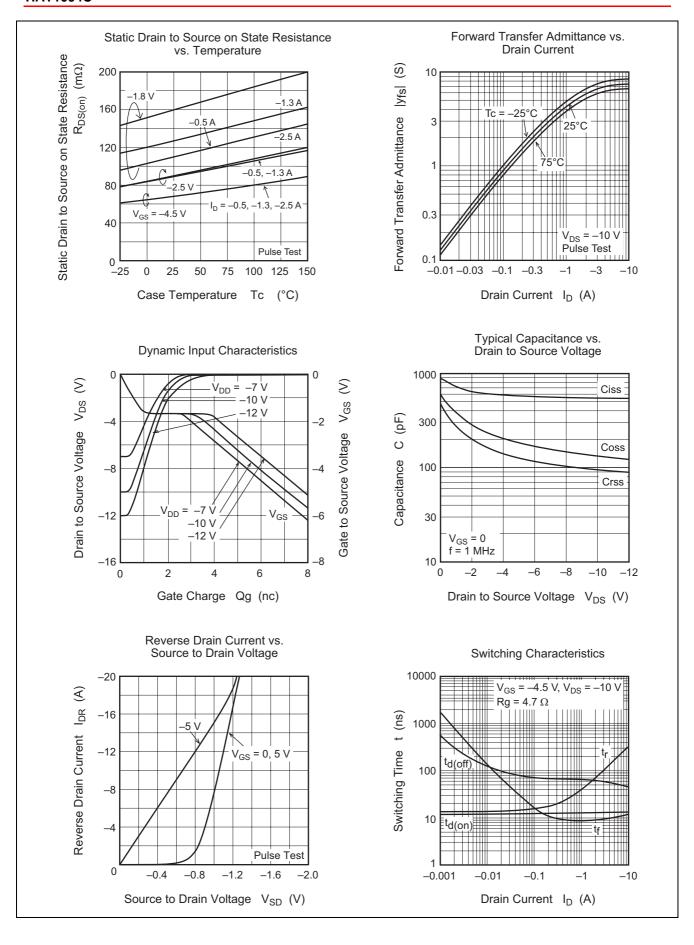
 $(Ta = 25^{\circ}C)$

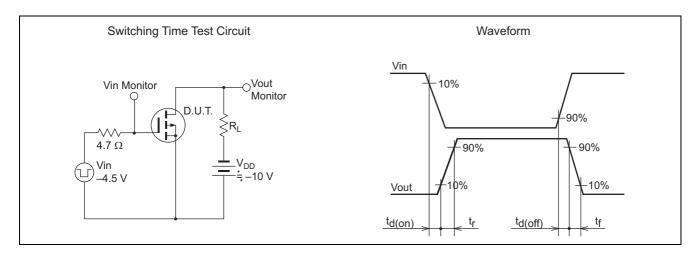
Item	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	-12			V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to Source breakdown voltage	$V_{(BR)GSS}$	±8			V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to Source leakage current	I _{GSS}			±10	μΑ	$V_{GS} = \pm 6.4 \text{ V}, V_{DS} = 0$
Drain to Source leakage current	I _{DSS}			-1	μΑ	$V_{DS} = -12 \text{ V}, V_{GS} = 0$
Gate to Source cutoff voltage	$V_{GS(th)}$	-0.3	_	-1.2	V	$I_D = -1 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Drain to Source on state resistance	R _{DS(on)}		67	88	mΩ	$I_D = -1.3 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$
		_	90	126	mΩ	$I_D = -1.3 \text{ A}, V_{GS} = -2.5 \text{ V}^{\text{Note3}}$
		_	128	192	mΩ	$I_D = -1.3 \text{ A}, V_{GS} = -1.8 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	3.5	5	_	S	$I_D = -1.3 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	530	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	130	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	95	_	pF	
Total gate charge	Qg	_	6.5	_	nC	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$
Gate to Source charge	Qgs	_	1	_	nC	$I_D = -2.5 \text{ A}$
Gate to Drain charge	Qgd	_	1.8	_	nC	
Turn - on delay time	t _{d(on)}	_	12	_	ns	$\begin{split} V_{DS} = -10 \ V, \ V_{GS} = -4.5 \ V, \\ I_{D} = -1.3 \ A, \ R_{L} = 7.7 \ \Omega, \\ R_{g} = 4.7 \ \Omega \end{split}$
Rise time	t _r	_	52	_	ns	
Turn - off delay time	t _{d(off)}	_	62	_	ns	
Fall time	t _f	_	9	_	ns	
Body - Drain diode forward voltage	V_{DF}	_	-0.85	-1.1	V	$I_F = -2.5 \text{ A}, V_{GS} = 0$

Notes: 3. Pulse test

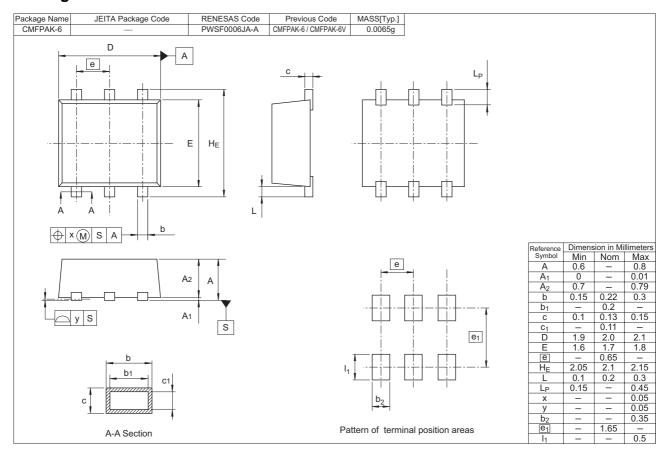
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1094C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510

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